





SPECIFICATION FOR 1.8V LVDS SMT TCXO MtronPTI P/N M6302S039

Electrical Specifications:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		300.000000		MHz	
Frequency Tolerance		-1.0		+1.0	ppm	@ +25°C
		F	requency Sta	bility		
vs. Temperature	ΔF/F			4.6	ppm	(Max-Min)/2
vs. Aging		-3		+3	ppm	1 st year
vs. Aging		-1		+1	ppm	Per year thereafter.
			RF Outpu	t		
Output Type	Differential LVDS Compatible			patible		
Output Load		100 Ω Differential			V	
Common Mode Output Voltage	·			V		
Differential Output Voltage		250	425	500	mV	LVDS Load
Symmetry (duty cycle)	T _{DC}	45		55	%	Referenced to 1.2 V
Rise/Fall Time	T_R/T_F			0.35	nS	From 20% to 80% Vcc
	S	upply Vo	Itage & Powe	r Consum	nption	
Operating Voltage	V _{cc}	1.71	1.80	1.89	V	
Operating Current	I _{cc}			100	mA	

Environmental Conditions:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Operating Temperature	TA	-55		+125	°C	
Storage Temperature	Ts	-55		+125	°C	
Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms duration, ½ sinewave)					
Vibration	Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)					
Thermal Shock	Per MIL-STD-883, Method 1011, Condition A					
Thermal Cycle	Per MIL-STD-883, Method 1010, Condition B					
Hermeticity	Per MIL-STD-202, Method 112 (1 x 10 ⁻⁸ atm cc/s of helium)					
Moisture Sensitivity Level (MSL)	MSL 1					
Solderability	Per EIAJ-STD-002					
Max. Soldering Conditions	See Figure 1.					
Package Type	/pe 6-pad 5.0 X 7.0 X 1.9 mm leadless ceramic. RoHS compliant.					

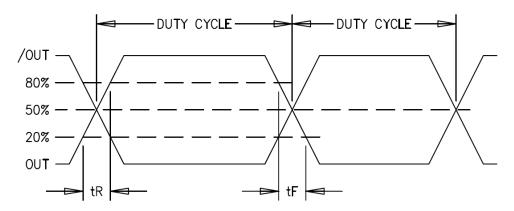




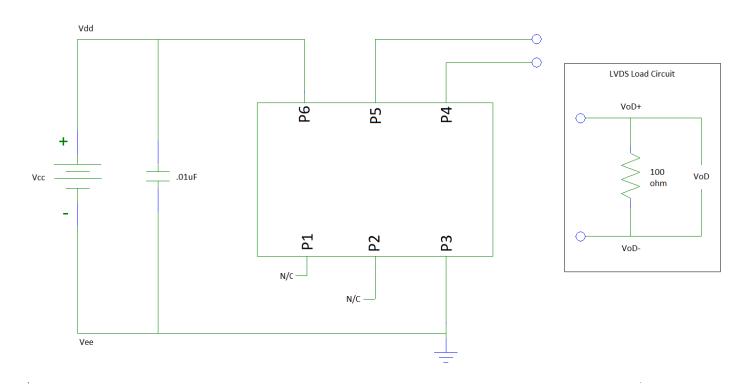


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Output Waveform:



Typical Test Circuit & Load Circuit Diagrams:









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Soldering Conditions:

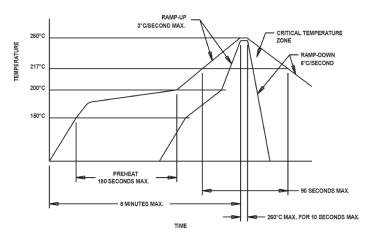
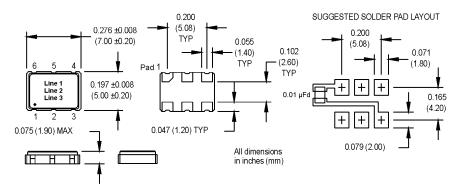


Figure 1

Mechanical, Marking, and Pin Out Information:



Datasheet Revision Table:

	Date	Rev.	Author	Details of Revision	
05/	/13/20	0	MM	Original release.	